

Product Advisory (PA)

Subject: Change of the standard interior label of Renesas Electronics

Publication Date: December 1, 2022

Effective Date: Refer to Appendix A to D

Revision Description:

Initial Release

Description of Change:

Renesas Electronics will update and streamline the standard interior labels in shipments for all products in conjunction with our systems integration plan.

Kindly refer to Appendix A to D for comparison on the current and new standard labels.

Materials related to 2D barcode specifications is available upon request.

Affected Product List:

All products, including legacy Intersil, IDT, Dialog and Renesas except custom-labeled products.

Reason for Change:

To integrate company-wide standard labels through the integration of SCM systems, including logistic systems.

Impact on Fit, Form, Function, Quality & Reliability:

This change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

Qualification Status: Not applicable

Sample Availability Date: Not applicable

Device Material Declaration: Not applicable

Questions or requests pertaining to this change notice, including additional data, must be sent to Renesas within 30 days of the publication date.

APPENDIX A: LEGACY INTERSIL PRODUCTS

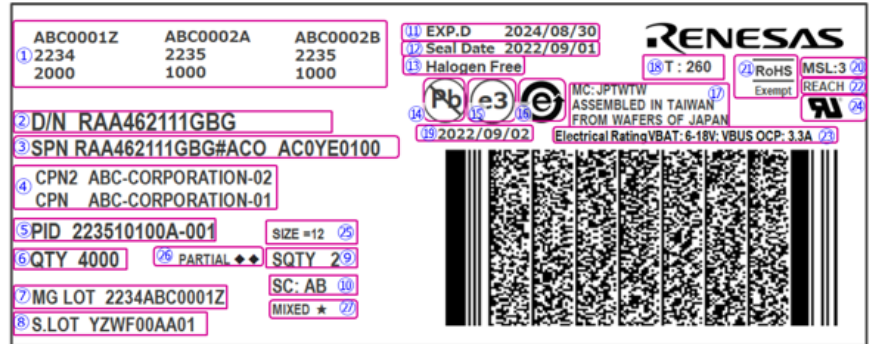
Effective Date: August 1, 2023

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign



Comparison before and after change for legacy INTERSIL products

Gap Points Current and New / Ex-ISL

For Finished Goods

For Wafer Sales

42mm

10mm

32mm

For Wafer Sales

100mm

100mm

Gap Points

- Added Items
 - PID (Traceability Control)
 - S.LOT (Traceability Control) For Renesas Internal Use
 - Add RoHS / RoHS Exempt (Display RoHS or RoHS Exempt)
 - Add China RoHS (Display China RoHS Certified)
- Design Change Items
 - SPN (Orderable Parts No.)
 - CPN/CPN2 (Customer Parts No.)
 - Lot Combine Information
 - Country of Origin (Manufacturing Country Info.)
 - PCB On Board Reflow Rank (Peak Temperature)
 - MG LOT (Manufacturing Lot No.)

For additional information regarding this notice, please contact your regional change coordinator (below)

Americas: PCN-US@Renesas.COM	Europe: PCN-EU@Renesas.COM	Japan: PCN-JP@Renesas.COM	Asia Pac: PCN-APAC@Renesas.COM
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APPENDIX B: LEGACY IDT PRODUCTS

Effective Date: August 1, 2023

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item


Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign



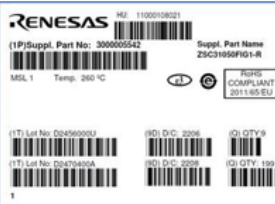
Comparison before and after change for legacy IDT products

Gap Points Current and New / Ex-IDT


For Finished Goods





For Wafer Sales



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Gap Points

- Added Items
 - PID (Traceability Control)
 - S.LOT (Traceability Control)
 - For Renesas Internal Use
- Design Change Items
 - SPN (Orderable Parts No.)
 - Lot Combine Information
 - MG LOT (Manufacturing Lot No.)
 - Pb-Free's Logo Mark
 - Country of Origin (Manufacturing Country Info.)
 - PCB On Board Reflow Rank (Peak Temperature)

For additional information regarding this notice, please contact Idt-pcn@lm.renesas.com.

APPENDIX C: LEGACY DIALOG PRODUCTS

Effective Date: August 1, 2023

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign



Comparison before and after change for legacy DIALOG products

Gap Points Current and New / Ex-DLG

For Finished Goods

For Wafer Sales

Gap Points

- Added Items
 - PID (Traceability Control)
 - EXP. Date (Traceability Control) For Renesas Internal Use
 - S.LOT (Traceability Control) For Renesas Internal Use
- Design Change Items
 - Renesas Logo Mark
 - SPN (Orderable Parts No.)
 - CPN/CPN2 (Customer Parts No.)
 - MG LOT (Manufacturing Lot No.)
 - Lot Combine Information
 - Country of Origin (Manufacturing Country Info.)
 - PCB On Board Reflow Rank (Peak Temperature)
 - SC (Test Supplier Code)

For additional information regarding this notice, please contact your Renesas sales representative.

APPENDIX D: LEGACY RENESAS PRODUCTS

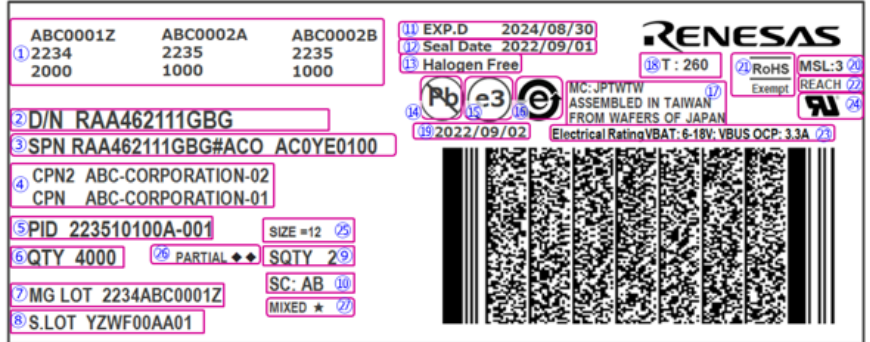
Effective Date: April 1, 2024

Product Identification:

The new standard label after the change is as follows.

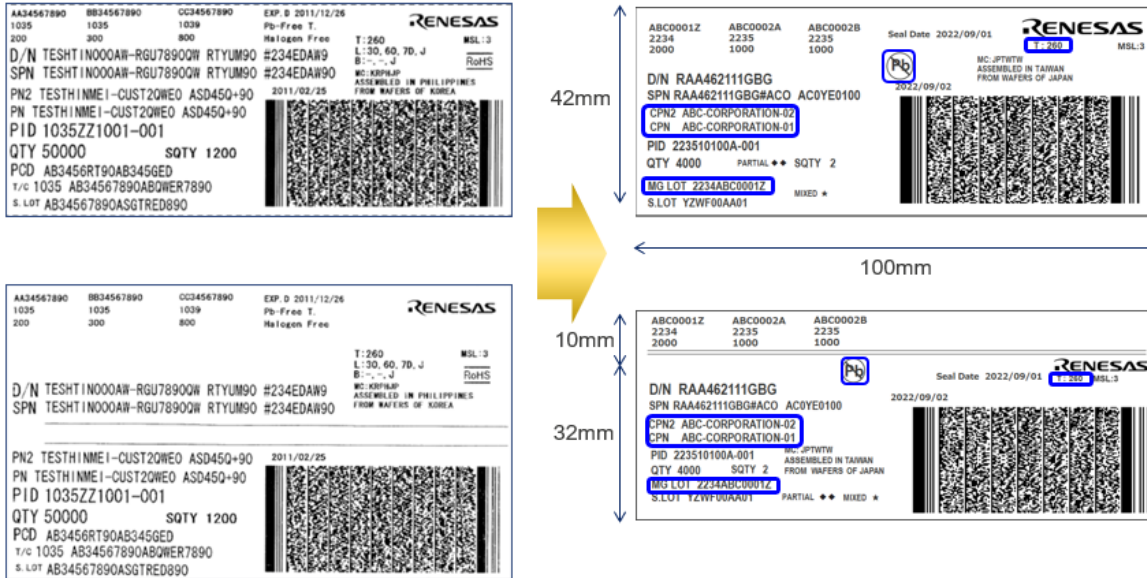
Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign



Comparison before and after change for legacy RENESAS products

Gap Points Current and New / Renesas Japan (REL)



Gap Points

- Design Change Items
 - Pb-Free's Logo Mark
 - PCB On Board Reflow Rank (Peak Temperature)
 - Customer Parts No. (Display Name Change)
 - PN/PN2 => CPN/CPN2
 - MG LOT (Display Name Change)
 - T/C => MG LOT
 - PCN (Deleted Item)

For additional information regarding this notice, please contact your Renesas sales representative.